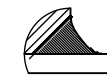
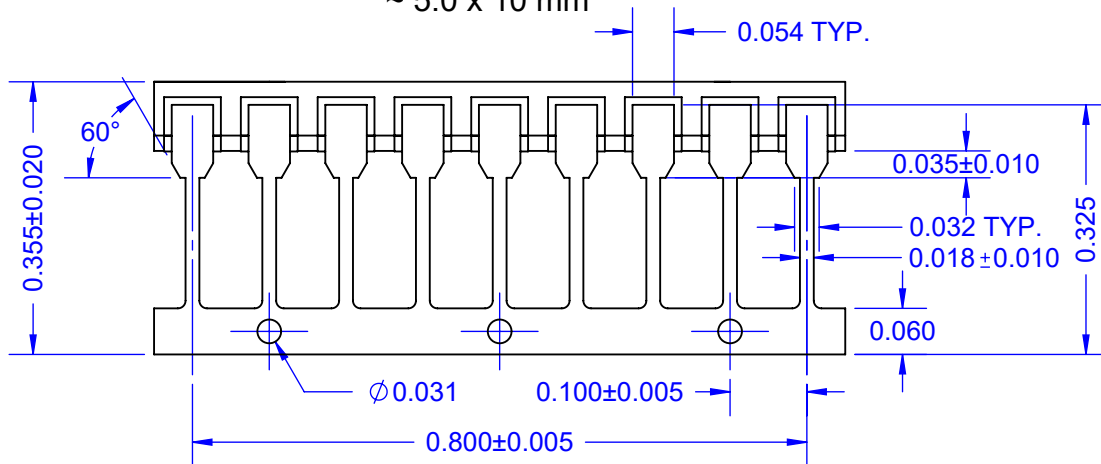


DIE PAD
0.200 x 0.390-inch
~ 5.0 x 10 mm



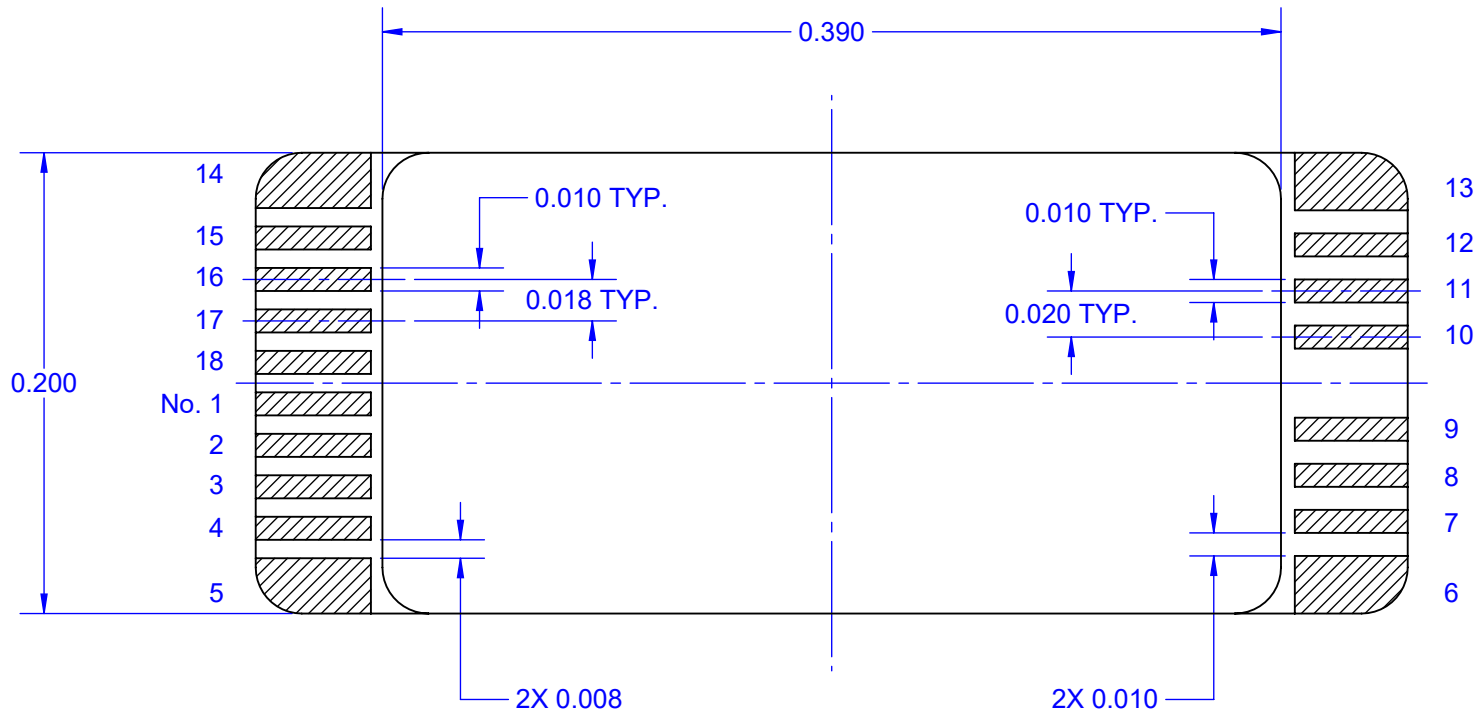
DETAIL B
SCALE 10 : 1

- NOTES: (Unless Otherwise Specified).
1. GOLD PLATE 60 micro-inch over 100 micro-inch (MIN) NICKEL.
 2. SEAL AREA TO BE METALLIZED.
 3. SEE PART NUMBER TABLE FOR DIE ATTACH METALLIZATION.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE: 0.35 OHM MAX.
 6. TOLERANCE ± 0.005 -INCH UNLESS OTHERWISE SPECIFIED.
 7. CERAMIC (Al_2O_3 BLACK) SIDE-BRAZE PACKAGE KOVAR LEAD FRAME WITH GOLD METALLIZATION.

PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP18F3-N200X390	GOLD	200390


APPROVALS	DATE	TopLine®			
DRAWN T. Au	1/28/2022				
ENG M. Hart	1/28/2022	TITLE CERDIP18F3-N200X390 DIE PAD 5.0mm x 10mm			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		4:1	A	200390	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

BONDING PADS

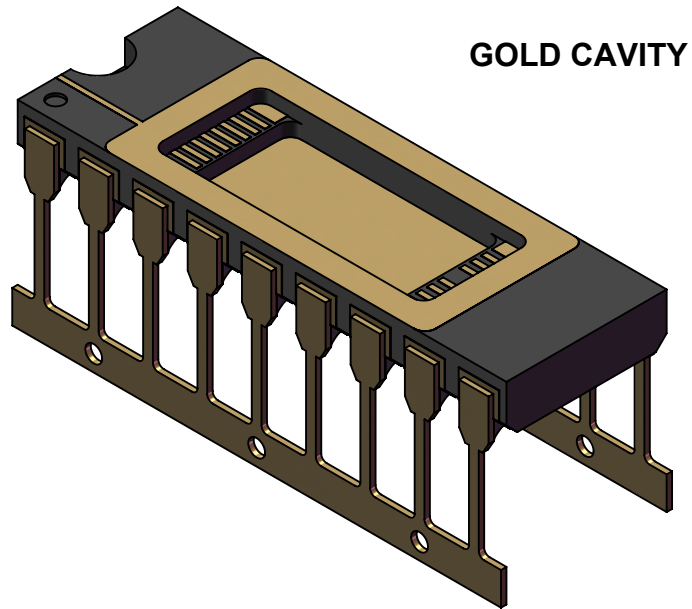


DIE PAD
0.232 x 0.537-inch
5.9 x 13.6 mm

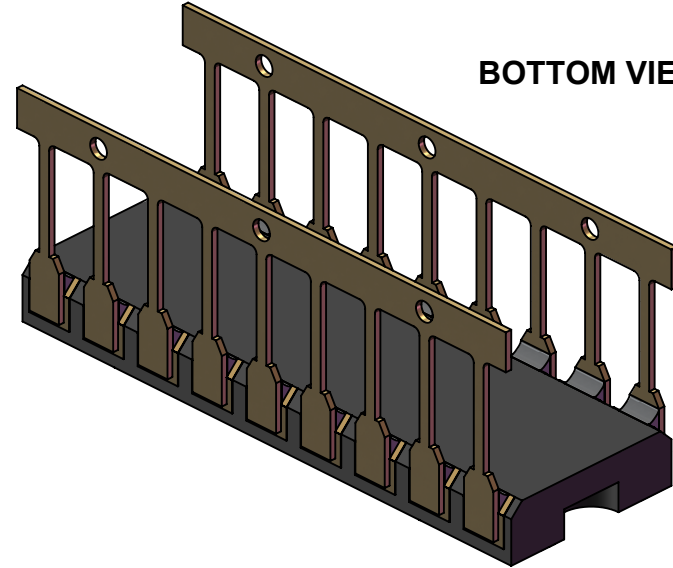
PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP18F3-N200X390	GOLD	200390

			
TITLE		CERDIP18F3-N200X390 DIE PAD 5.0mm x 10mm	
SCALE	SIZE	DRAWING NO.	REV
12:1	A	200390	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODELS




GOLD CAVITY



BOTTOM VIEW

PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP18F3-N200X390	GOLD	200390

			
TITLE		CERDIP18F3-N200X390 DIE PAD 5.0mm x 10mm	
SCALE	SIZE	DRAWING NO.	REV
4:1	A	200390	A
DO NOT SCALE DRAWING			SHEET 3 OF 3